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## Product Summary

<b>V<sub>BR</sub> min</b>	<b>I<sub>pp</sub> max</b>	<b>C<sub>in typ</sub></b>
6V	6A	15pF

## Description

This new generation TVS is designed to protect sensitive electronics from the damage due to ESD. The combination of small size and high ESD surge capability make it ideal for use in portable applications such as cellular phones, digital cameras and MP3 players.

## Applications

- Cellular Handsets
- Portable Electronics
- Computers and Peripheral

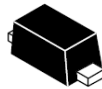
## Features

- Provides ESD Protection per IEC 61000-4-2 Standard: Air ±30kV, Contact ±30kV
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

## Mechanical Data

- Case: SOD923
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead-Free Plating). Solderable per MIL-STD-202, Method 208e3
- Weight: 0.001 grams (Approximate)

SOD923



Top View



Device Schematic

## Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
D5V0L1B2S9-7	Standard	S/S	7	8	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



S / S = Product Type Marking Code

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P <sub>PP</sub>	84	W	8/20μs, per Figure 1
Peak Pulse Current	I <sub>PP</sub>	6	A	8/20μs, per Figure 1
ESD Protection – Contact Discharge	V <sub>ESD_Contact</sub>	±30	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V <sub>ESD_Air</sub>	±30	kV	IEC 61000-4-2 Standard

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V <sub>RWM</sub>	—	—	5	V	—
Channel Leakage Current (Note 6)	I <sub>RM</sub>	—	10	100	nA	V <sub>RWM</sub> = 5V
Clamping Voltage, Positive Transients	V <sub>CL</sub>	—	7.0	9.0	V	I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μS
		—	8.7	10.7		I <sub>PP</sub> = 3A, t <sub>p</sub> = 8/20μS
		—	10.5	12.0		I <sub>PP</sub> = 5A, t <sub>p</sub> = 8/20μS
		—	11.5	14.0		I <sub>PP</sub> = 6A, t <sub>p</sub> = 8/20μS
Breakdown Voltage	V <sub>BR</sub>	6	7	8	V	I <sub>R</sub> = 1mA
Differential Resistance	R <sub>DIF</sub>	—	0.2	—	Ω	I <sub>R</sub> = 1A, t <sub>p</sub> = 8/20μS
Channel Input Capacitance	C <sub>IN</sub>	—	15	20	pF	V <sub>R</sub> = 0V, f = 1MHz

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.  
6. Short duration pulse test used to minimize self-heating effect.

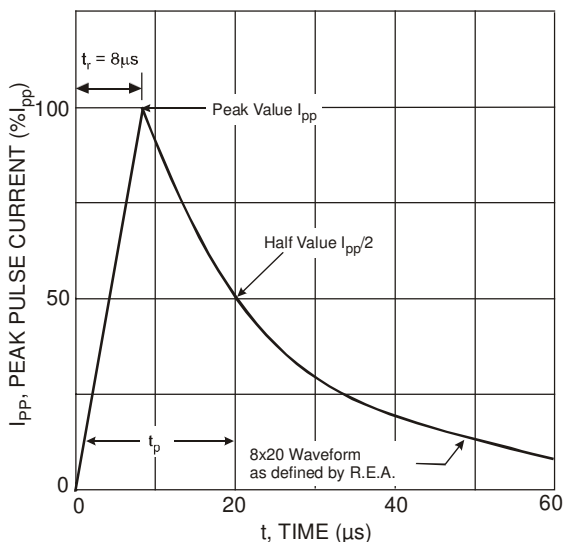


Figure 1 Pulse Waveform

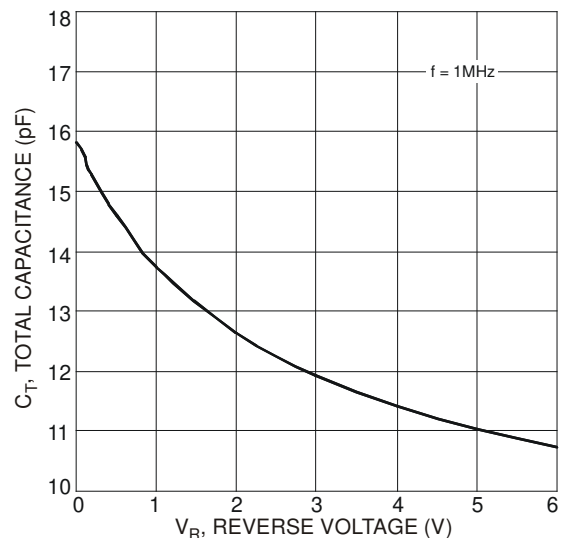


Figure 2 Typical Total Capacitance vs. Reverse Voltage

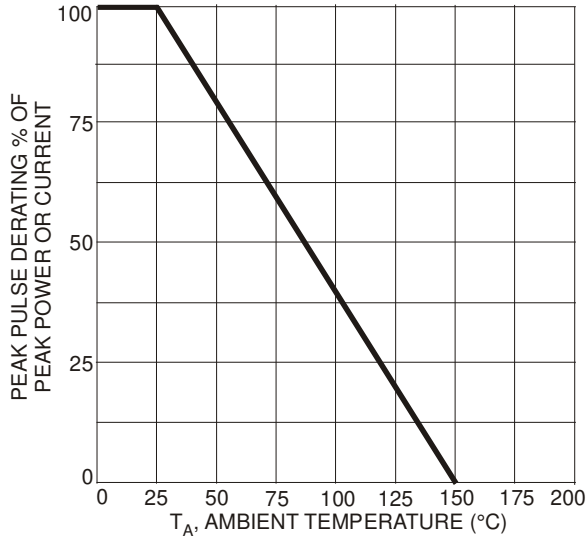


Figure 3 Pulse Derating Curve

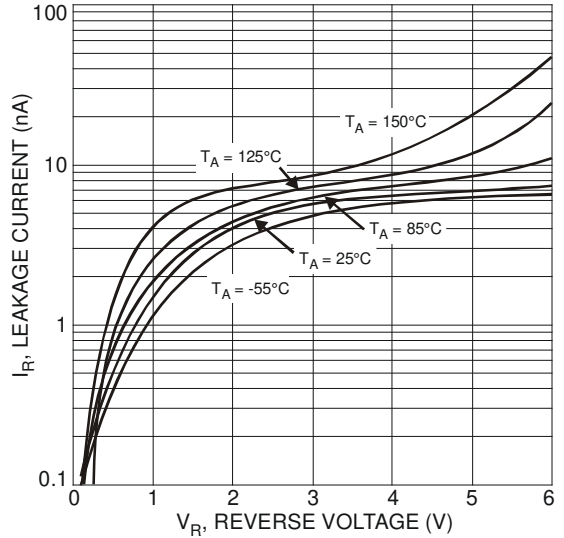


Figure 4 Typical Reverse Characteristics

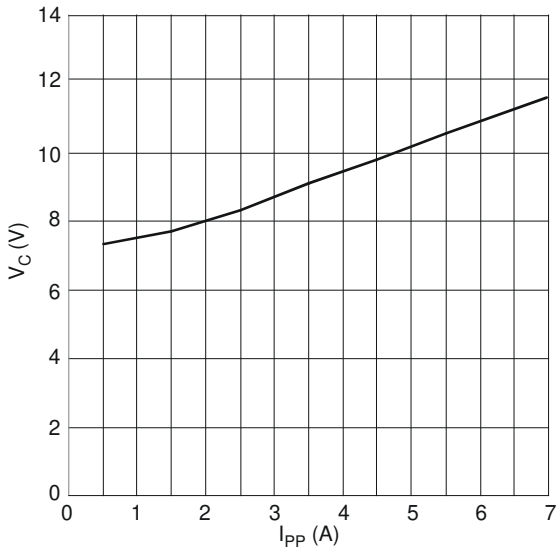


Figure 5 Typical Peak Clamping Voltage  $V_C$  vs. Peak Pulse Current  $I_{PP}$

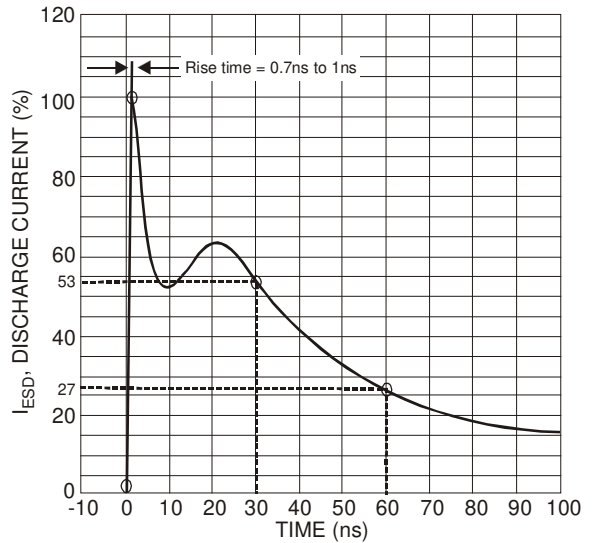


Figure 6 ESD Discharge Current Wave Form IEC 61000-4-2 (330Ω/150pF)

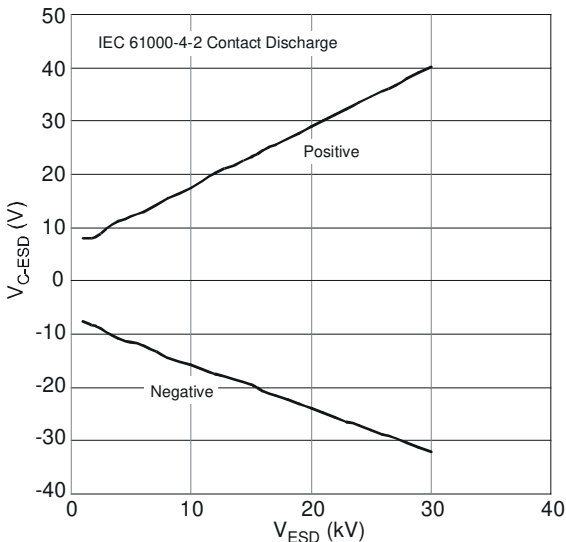


Figure 7 Typical Clamping Voltage vs. Contact Discharge Voltage

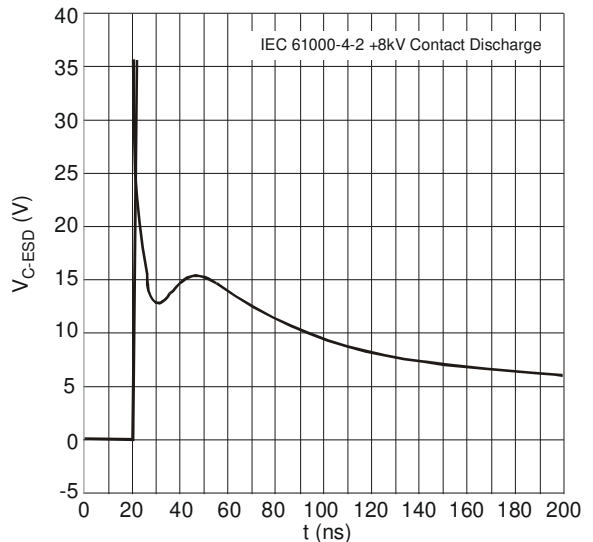


Figure 8 Typical Clamping Performance @ 8kV Contact Discharge

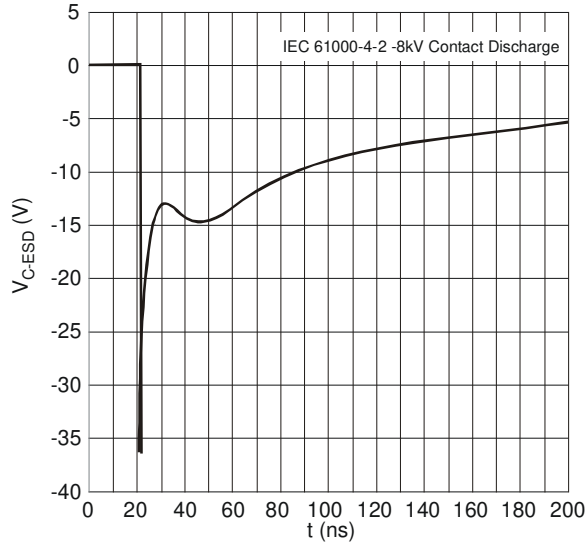
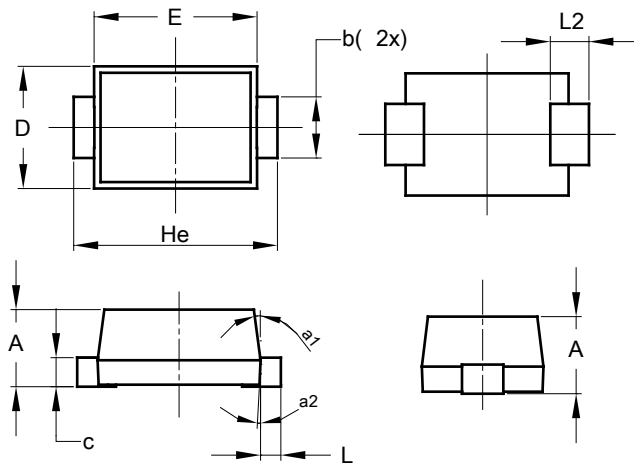


Figure 9 Typical Clamping Performance @ -8kV Contact Discharge

**Package Outline Dimensions**

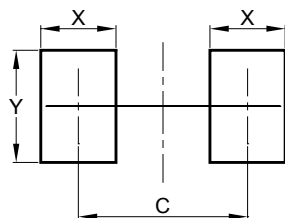
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOD923 (0.3mm Lead Width)			
Dim	Min	Max	Typ
A	0.34	0.40	0.37
b	0.25	0.35	0.30
c	0.05	0.15	0.10
D	0.55	0.65	0.60
E	0.75	0.85	0.80
He	0.95	1.05	1.00
L	0.05	0.15	0.10
L2	0.190 REF		
a1	0°	8°	7°
a2	2°	4°	3°
All Dimensions in mm			

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.



Dimensions	Value (in mm)
C	0.900
X	0.400
Y	0.600

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